



Minutes of P-10 Integrated Passive Devices

Tuesday, 20 April, 2004

Hilton Tampa Westshore

Tampa, FL

P-10 Committee's Scope:

Will provide technical support and develops standards and specifications for electronic devices using mixed passive product technologies and diodes that perform a passive function, e.g., a) resistors and capacitors; b) resistors and diodes; c) resistors, capacitors, and inductors.

These devices may be discrete components that are “integrated” on a common substrate (hybrid) or in a carrier formed by a common manufacturing process (monolithic).

Activities also include the generation of terms and definitions, review of specifications, establishment of new specification criteria, and maintenance of existing criteria relating to these devices.

To accomplish these functions, the committee maintains liaison with and uses technical information from other standards development organizations (SDOs), government agencies, industry, various professional organizations, participating members, and guests

Attendees:

NAME	COMPANY
Susan Barkal	Kemet
Ted Coler	Vishay
Michael Griffith	KOA
Nick Holmberg	Intel Corporation
Joe Kroog	IHS
Carl Lindquist	San-O-Industrial Corp
Len Metzger	Panasonic Industrial Co
Stephen Olster	Mini-Systems Inc.
Brian Piscitelli	KOA Speer Electronics
Chris Reynolds	AVX
Dave Ritchey	Yageo
Liwu Wang	AEM, Inc.

The meeting was called-to-order at 11:10 am by Chairman Brian Piscitelli

1. Introductions

2. Committee Organization and Procedures

2.1 Membership and Attendance

Attendance was taken, and it was determined that a quorum was present.

<u>Member Organizations Present</u>	<u>Present at this meeting</u>	<u>Present at previous meeting?</u>	<u>Present at meeting prior to previous?</u>
AEM, Inc.	Y	N	Y
AVX	Y	Y	N
Intel Corporation*	Y	n/a	n/a
Kemet	Y	N	N
KOA Speer Electronics	Y	Y	Y
Mini-Systems Inc.	Y	N	Y
Panasonic Industrial Co	Y	Y	Y
San-O-Industrial Corp	Y	Y	Y
Vishay	Y	Y	Y
Yageo	Y	Y	Y

***Indicates activated as member of committee**

<u>Member Organizations Absent</u>	<u>Present at This Meeting?</u>	<u>Present at previous meeting?</u>	<u>Present at meeting prior to previous?</u>
Cornell Dubilier	N	N	Y
IBM	N	Y	Y
KRFM America	N	Y	n/a
Maxwell Technologies	N	N	Y
Murata	N	Y	Y
SEI Electronics	N	Y	N
TDK	N	N	Y
Visteon	N	N	Y

*** Indicates not used in determination of quorum due to record of non-attendance**

<u>Other Organizations Present</u>
EIA/ECA
IHS

2.2 Approval of Agenda

The Committee unanimously accepted the Agenda as presented.

2.3 Approval of October, 2003 Meeting Minutes

The Committee unanimously accepted the Minutes of the last meeting as written.

2.4 Correspondence

No correspondence was received.

3. Old Business

3.1 Status of PN-4944 (RC test performance spec) for EDEC approval

Went out for letter ballot on January 23 2004. Received responses and a few comments, not all members received a copy of the letter ballot. IBM (comments), Mini-Systems (Comments), Bussman (abstain), KOA (approve). There was an issue brought up that not all of the people that the letter ballot is being sent to are the appropriate folks to vote. Chairman to define the core voting list for balloting.

IBM:

EIA formatting – performed by EIA (approved)

Requested to ref solderability to ref. J-STD-002 method 208 instead of Mil standard (approved)

Remove list of suppliers from the spec (approved)

MINI-SYSTEMS

corrections to 2.0 under applicable documents. Add J-STD reference and insure that all reference documents have correct titles (approved)

3.2.7 removing .3 from this reference (approved)

All changes were approved by the members. All current individuals at the current meeting and those from the last meeting will be included for letter balloting and are considered to be the core voting list.

Core Ballot list

Ted Coler (vishay) ted.coler@vishay.com

Mike Lauri (IBM)

Susan Barkal (Kemet) susanbarkal@kemet.com

Joe Kroog (IHS) Josef.kroog@ihs.com

Nick Holmberg (Intel) Nicholas.l.holmberg@intel.com

Stephen Olster (Mini-Systems) solster@mini-systemsinc.com

Len Metzger (Panasonic) metzgerl@us.panasonic.com

Dave Ritchey (Yageo) dave.n.ritchey@yageo.com

Carl Lindquist (San-o Industrial) fuseman@attglobal.net

Liwu Wang (AEM) lwang@aem-usa.com

Brian Piscitelli (KOA) bpiscitelli@koaspeer.com

Chris Reynolds (AVX) creynolds@avxus.com

IPD Chip Scale Package Test (PN-4996):

Went out for letter ballot in January 2004. Received a few responses but not all members had seen the ballot to vote on the spec. . Chairman to define the core voting list for balloting.

IBM

sample size in Table 1 are to low – requested samples size of 40pcs and total 120pcs (3 lots) currently listed as 10pcs and a total of 30pcs in the spec 4 of the tests. (moved to change to 40/120 – approved)

All changes were approved by the members. All current individuals at the current meeting and those from the last meeting will be included for letter balloting and are considered to be the core voting list.

Core-Ballot list

Ted Coler (vishay) ted.coler@vishay.com

Mike lauri (IBM)

Susan Barkal (Kemet) susanbarkal@kemet.com

Joe Kroog (IHS) Josef.kroog@ihs.com

Nick Holmberg (Intel) Nicholas.l.holmberg@intel.com

Stephen Olster (Mini-Systems) solster@mini-systemsinc.com

Len Metzger (Panasonic) metzgerl@us.panasonic.com

Dave Ritchey (Yageo) dave.n.ritchey@yageo.com

Carl Lindquist (San-o Industrial) fuseman@attglobal.net

Liwn Wang (AEM) lwang@aem-usa.com

Brian Piscitelli (KOA) bpiscitelli@koaspeer.com

Chris Reynolds (AVX) creynolds@avxus.com

3.2 IPD Application Guideline status

The application guideline has not been started moved to Mr Piscitelli to send out a preliminary outline of the format for the application guideline to the working group (Steve Olster, Randy Pinkleman & Ted Coler) – nothing was done since the last meeting. Mr. Piscitelli to send out preliminary outline by Oct. 2004

3.3 Other business

Handouts of the current listing of drawings, for integrated type packaging, in PDP-100 were submitted to the members for review. Michael Griffith (KOA) and Dave Ritchey (Yageo) to review these drawings and update drawings and EIA numbering to conform to the new P-4 mechanical outline guideline.

3.4 Review additional IPD Circuit Registration Requests

No new IPD registrations have been received.

4. New Business

A new NEDA (National Electronics Distributor Association) guideline is being created and a voice conference is set up for 28-April 2004 for members of the NEDA group. Upon the completion of this conference the guideline will be submitted to P-10 for comments. Tentative date for submission to P-10 group is 1-June-04. The file will be sent to those who attended the April 2004 meeting.

5. Future Meetings

Fall 2004, 04-07 October 2004 San Diego, CA, Holiday Inn On-the-Bay

6. Adjournment

The meeting was adjourned at 11:46 AM.

This meeting was conducted in accordance with the EIA Legal Guidelines and the Manual of Organization and Procedures.

Brian Piscitelli
Chairman

Michael Griffith
Acting Secretary